

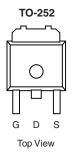
# SM6012NSU-VB Datasheet N-Channel 60-V (D-S) MOSFET

PRODUCT	SUMMARY	
V <sub>DS</sub> (V)	r <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A) <sup>a</sup>
60	0.025 at V <sub>GS</sub> = 10 V	45
30	0.030 at V <sub>GS</sub> = 4.5 V	40

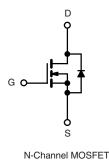
#### FEATURES

- Trench Power MOSFET
- 175 °C Junction Temperature





Drain Connected to Tab



T<sub>J</sub>, T<sub>stg</sub>

- 55 to 175

**ABSOLUTE MAXIMUM RATINGS**  $T_C = 25$  °C, unless otherwise noted Parameter Symbol Limit Unit Gate-Source Voltage  $V_{GS}$ ± 20 ٧ T<sub>C</sub> = 25 °C 45 Continuous Drain Current  $(T_J = 175 \ ^{\circ}C)^b$  $I_D$  $T_C = 100 \ ^{\circ}C$ 35 Pulsed Drain Current 100 А I<sub>DM</sub> Continuous Source Current (Diode Conduction)  $I_{S}$ 23 Avalanche Current 20 I<sub>AS</sub> Single Avalanche Energy (Duty Cycle  $\leq$  1 %) L = 0.1 mH $\mathsf{E}_{\mathsf{AS}}$ 20 mJ T<sub>C</sub> = 25 °C 100 Maximum Power Dissipation  $\mathsf{P}_\mathsf{D}$ W T<sub>A</sub> = 25 °C 3<sup>a</sup>

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient <sup>a</sup>	$t \le 10 \text{ sec}$	R <sub>thJA</sub>	18	22	
Maximum Junction-to-Ambient*	Steady State		40	50	°C/W
Maximum Junction-to-Case		R <sub>thJC</sub>	3.2	4	

Notes:

a. Surface Mounted on 1" x 1" FR4 board, t  $\leq$  10 sec.

Operating Junction and Storage Temperature Range

°C

<b>SPECIFICATIONS</b> $T_J = 25$ Parameter	Symbol	Test Conditions	Min	Trund	Max	Unit	
	Symbol	Test Conditions	INITI	Тур <sup>а</sup>	wax	Unit	
Static	L V	V 0.V L 250 vA					
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0 V, I_D = 250 \mu A$	60		3.0	v	
Gate Threshold Voltage	V <sub>GS(th)</sub>	50 60 5	$V_{\rm DS} = V_{\rm GS}, I_{\rm D} = 250 \mu {\rm A}$ 1.0 2.0				
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
		$V_{DS} = 60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 ^{\circ}\text{C}$			50	μΑ	
		$V_{DS} = 60$ V, $V_{GS} = 0$ V, $T_{J} = 175$ °C			250		
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	$V_{DS} = 5 V, V_{GS} = 10 V$	50			А	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 15 A		0.025			
	r	$V_{GS}$ = 10 V, I <sub>D</sub> = 15 A, T <sub>J</sub> = 125 °C		0.055		Ω S	
Drain-Source On-State Resistance <sup>b</sup>	r <sub>DS(on)</sub>	$V_{GS}$ = 10 V, I <sub>D</sub> = 15 A, T <sub>J</sub> = 175 °C		0.069		52	
		$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 10 \text{ A}$		0.030			
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 15 A		20		S	
Dynamic <sup>a</sup>	•						
Input Capacitance	C <sub>iss</sub>			1500			
Output Capacitance	C <sub>oss</sub>	$C_{oss}$ V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 25 V, f = 1 MHz		140		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			60		1	
Total Gate Charge <sup>c</sup>	Qg			11	17		
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 23 \text{ A}$		3		nC	
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			3		1	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			8	15		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 30 \text{ V}, \text{ R}_{L} = 1.3 \Omega$		15	25	- ns	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 23 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		30	45		
Fall Time <sup>c</sup>	t <sub>f</sub>	1		25	40		
Source-Drain Diode Ratings and Cha	aracteristics	(T <sub>C</sub> = 25 °C)		<u> </u>			
Pulsed Current	I <sub>SM</sub>				50	А	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>F</sub> = 15 A, V <sub>GS</sub> = 0 V		1.0	1.5	V	
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 15 A, di/dt = 100 A/μs		30	60	ns	

Notes:

a. For design aid only; not subject to production testing.

b. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

c. Independent of operating temperature.

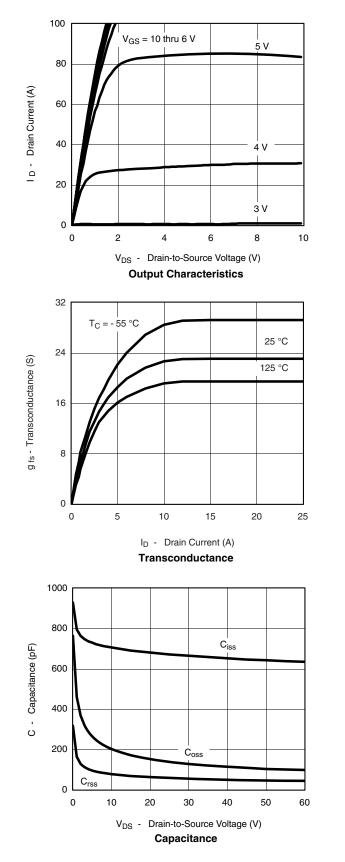
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

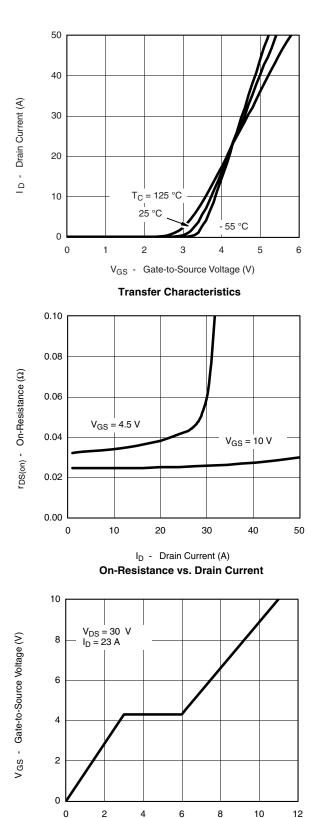
emi

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#### TYPICAL CHARACTERISTICS 25 °C unless noted





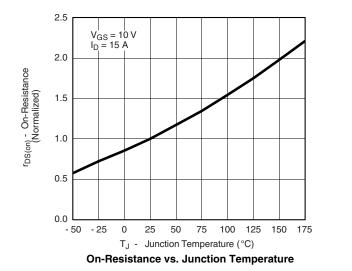
Qg - Total Gate Charge (nC)

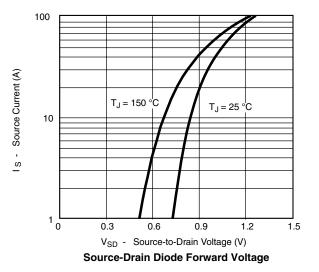
Gate Charge

服务热线:400-655-8788



### TYPICAL CHARACTERISTICS 25 °C unless noted





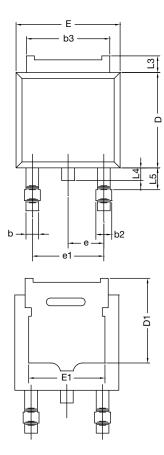


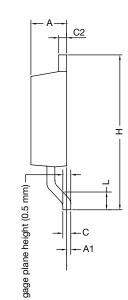
#### **THERMAL RATINGS**





# **TO-252AA CASE OUTLINE**





	MILLIMETERS		INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
А	2.18	2.38	0.086	0.094	
A1	-	0.127	-	0.005	
b	0.64	0.88	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	
С	0.46	0.61	0.018	0.024	
C2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	
D1	5.21	-	0.205	-	
Е	6.35	6.73	0.250	0.265	
E1	4.32	-	0.170	-	
Н	9.40	10.41	0.370	0.410	
е	2.28 BSC		0.090 BSC		
e1	4.56	4.56 BSC		0.180 BSC	
L	1.40	1.78	0.055	0.070	
L3	0.89	1.27	0.035	0.050	
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	
ECN: X12- DWG: 534	0247-Rev. M, 7	24-Dec-12	· · · · · · · · · · · · · · · · · · ·		

Note

• Dimension L3 is for reference only.



## **RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)**



Recommended Minimum Pads Dimensions in Inches/(mm)



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